



In re Application of:
Chang, et al.

Group Art Unit: 1762

Examiner: Unknown

For: Ruthenium Layer
Formation for Copper Film
Deposition

MAIL STOP NON-FEE AMENDMENT
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Dear Sir:

Prior to examination, please amend the above-identified application as shown in the following pages. Amendments to the Specification begin on page 2. Remarks begin on page 3.